

**ABSTRACT OF THE DISCLOSURE**  
**METHOD OF ASSEMBLING A STACKED DIE SEMICONDUCTOR**  
**PACKAGE**

A method of manufacturing a plurality of stacked die semiconductor packages, including: attaching a second silicon wafer to a first silicon wafer, wherein the second silicon wafer has a plurality of open vias; attaching a third silicon wafer to the second silicon wafer, wherein the third silicon wafer has a plurality of open vias, and the open vias of the second and third silicon wafers are aligned with one another; etching a bonding material that attaches the wafers from the aligned open vias; filling the aligned open vias with a conductor; forming conductive bumps at open ends of the aligned open vias; back grinding the first silicon wafer; separating the stacked semiconductor dies from each other; attaching the bump end of the stacked semiconductor dies onto a substrate; encapsulating the stacked semiconductor dies and substrate; and singulating the encapsulated assembly.

FIGURE 1



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